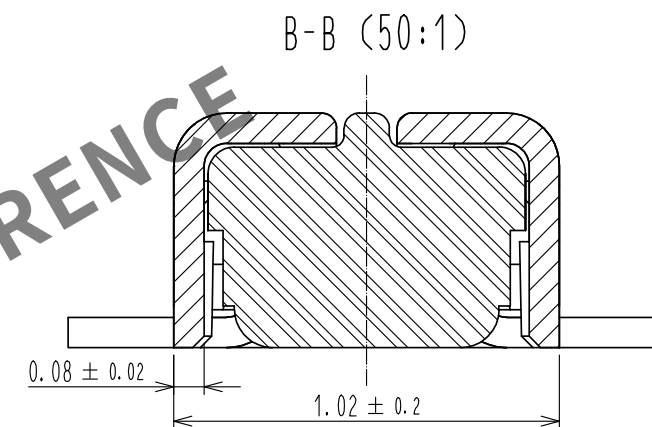
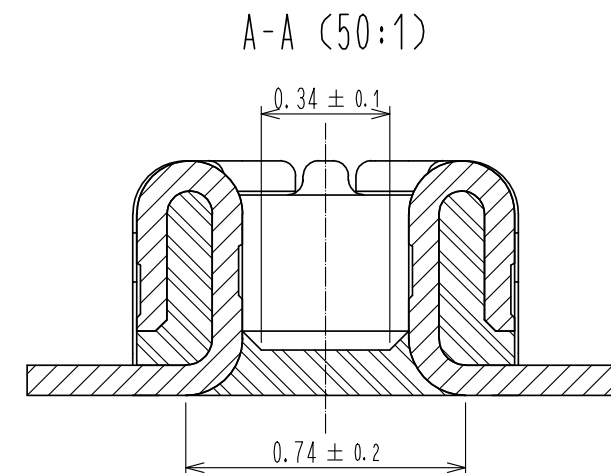
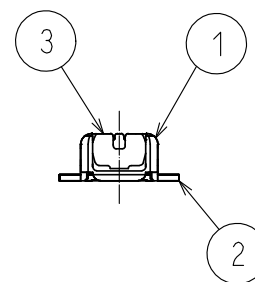
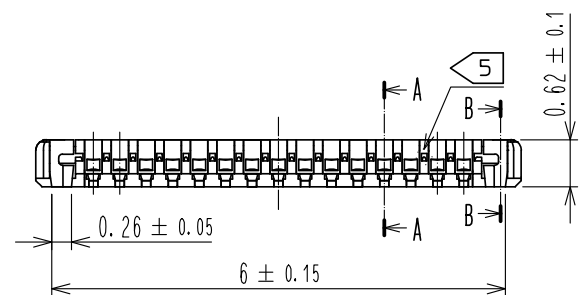
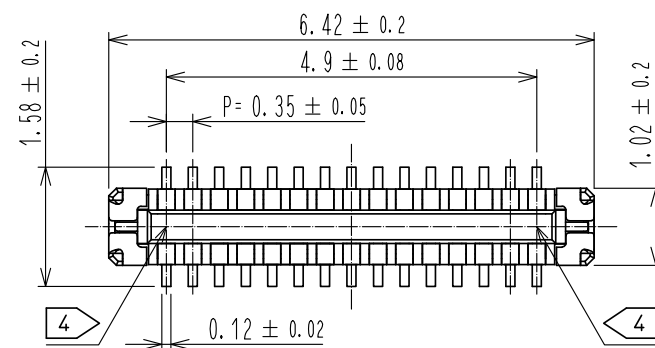
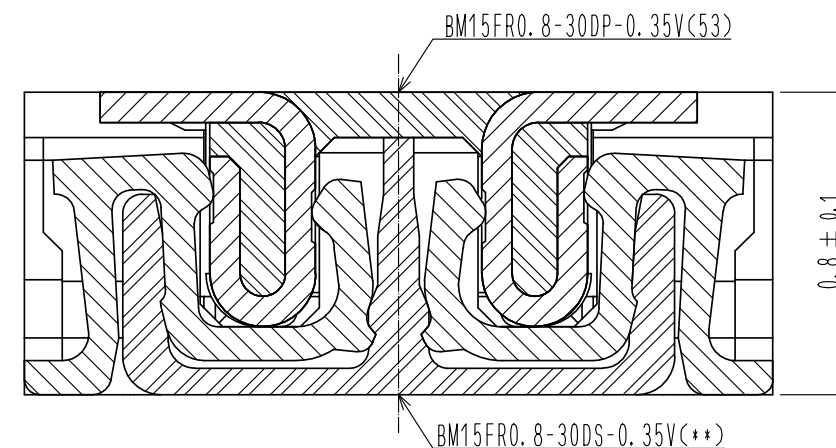




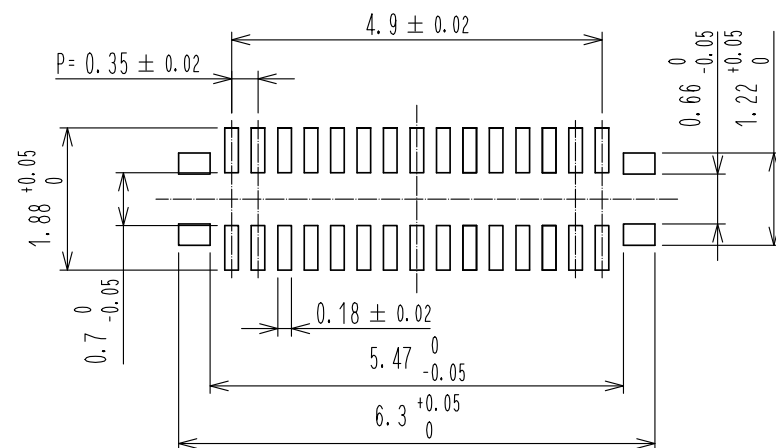
ENGAGEMENT FIGURE (50:1)



- NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2. CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05μm MIN
SMT LEAD : GOLD 0.05μm MIN
UNDERPLATING : NICKEL 1μm MIN
(SURFACE : SEALING)
3. REINFORCED METAL FITTINGS LOCK
SMT LEAD : GOLD 0.05μm MIN
UNDERPLATING : NICKEL 1μm MIN
(SURFACE : SEALING)
4. CAV No. AND HRS MARK MYE BE INDICATED IN APPROX POSITION SHOWN.
5. A PART OF THE WALL COULD BE NOTCHED.

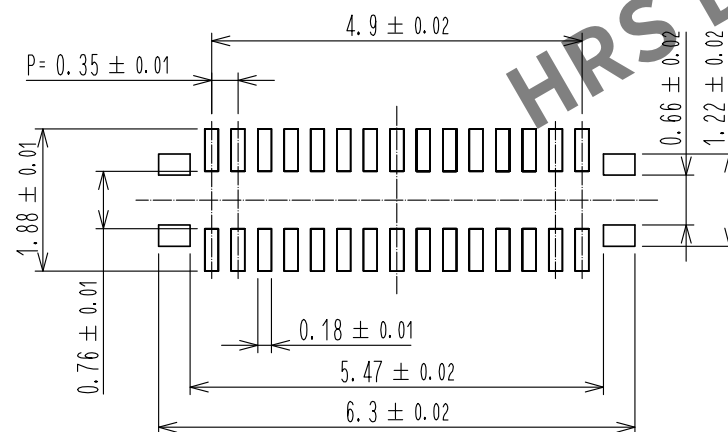
4	PS	CLEAR (ENBOSSED CARRIER TAPE)			
3	PHOSPHOR BRONZE	3	7	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 10 : 1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED
HIROSE ELECTRIC CO., LTD.		APPROVED : MO. ISHIDA	16. 01. 08	DRAWING NO.	EDC-356366-53-01
		CHECKED : TS. MIYAZAKI	16. 01. 08	PART NO.	BM15FR0.8-30DP-0.35V(53)
		DESIGNED : SH. HOSODA	16. 01. 07	CODE NO.	CL673-1243-7-53
		DRAWN : KR. AJITO	16. 01. 07		
					1/3

◆ RECOMMENDED PCB LAYOUT

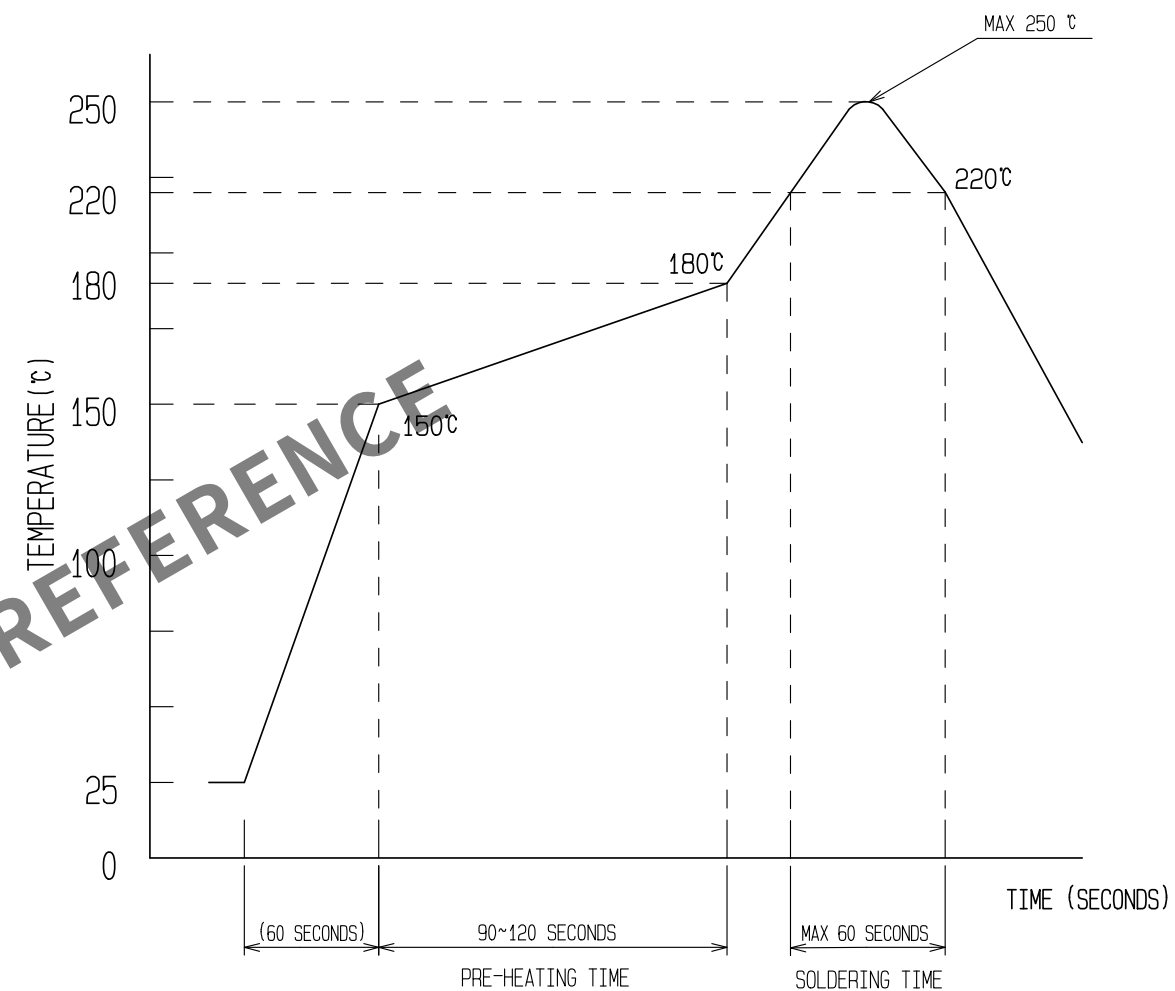


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : $100 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

- 1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC. MAX.
(PEAK TEMPERATURE: 250°C MAX)
- 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90~120 sec.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC-356366-53-01
PART NO.	BM15FR0.8-30DP-0.35V(53)
CODE NO.	CL673-1243-7-53

